

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 17 March 2026, 15:40 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	4.8%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	3.57%	1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	6%
Encapsulation	EP (Epoxy resin)	25.92%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	14%
			SILVER, ELEMENTAL	7440-22-4	80%
			Carbon black	1333-86-4	0.85%
			Phenol, polymer with formaldehyde	9003-35-4	1.15%
			Silicon Dioxide	7631-86-9	4%
			Epoxy resin 89	26335-32-0	7%
			Quartz sand	60676-86-0	87%
Inner preparation	Wrought aluminium alloys	3.87%	ALUMINUM, ELEMENTAL	7429-90-5	100%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.72%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	5.81%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	55.31%	Elemental iron	7439-89-6	2.5%
			COPPER, ELEMENTAL	7440-50-8	97.5%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
QFN5x6 Pb&H-free Ag Al Cu	Diode / Transistor SMD	0.103	g
